

EMIF04-MMC02F2

4 LINES EMI FILTER INCLUDING ESD PROTECTION

IPADTM

MAIN PRODUCT CHARACTERISTICS:

Where EMI filtering in ESD sensitive equipment is required:

MultiMedia Card for mobile phones, Personal Digital Assistant, Digital Camera, MP3 players...

DESCRIPTION

The EMIF04-MMC02 is a highly integrated devices designed to suppress EMI/RFI noise for Multi-Media Card port. The EMIF04 flip chip packaging means the package size is equal to the die size. This filter includes an ESD protection circuitry which prevents the device from destruction when subjected to ESD surges up 15kV.

BENEFITS

- EMI symmetrical (I/O) low-pass filter
- High efficiency in EMI filtering
- Lead free package
- Very low PCB space consuming: 1.57 mm x 2.07 mm
- Very thin package: 0.65 mm
- High efficiency in ESD suppression
- High reliability offered by monolithic integration
- High reducing of parasitic elements through integration & wafer level packaging.

COMPLIES WITH THE FOLLOWING STANDARDS: IEC61000-4-2

Level 4 15kV (air discharge) 8kV (contact discharge)

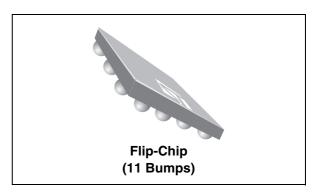


Table 1: Order Code

Part Number	Marking
EMIF04-MMC02F2	FH

Figure 1: Pin Configuration (ball side)

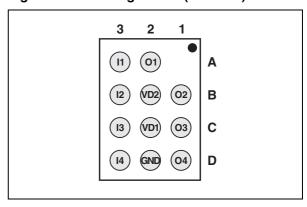
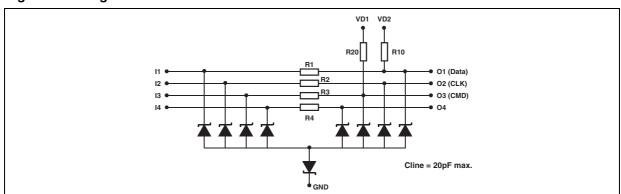


Figure 2: Configuration



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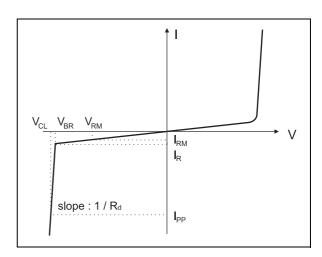
EMIF04-MMC02F2

Table 2: Absolute Ratings $(T_{amb} = 25^{\circ}C))$

Symbol	Parameter and test conditions	Value	Unit
P _R	DC power per resistor	70	mW
T _j	Maximum junction temperature	125	°C
T _{op}	Operating temperature range	- 40 to + 85	°C
T _{stg}	Storage temperature range	- 55 to + 150	°C

Table 3: Electrical Characteristics ($T_{amb} = 25^{\circ}C$)

Symbol	Parameter	
V _{BR}	Breakdown voltage	
I _{RM}	Leakage current @ V _{RM}	
V _{RM}	Stand-off voltage	
V _{CL}	Clamping voltage	
R _d	Dynamic impedance	
I _{PP}	Peak pulse current	
R _{I/O}	Series resistance between Input & Output	
C _{line}	Input capacitance per line	



Symbol	Test conditions	Min.	Тур.	Max.	Unit
V _{BR}	I _R = 1 mA	6			V
I _{RM}	V _{RM} = 3V		100	500	nA
C _{line}	@ 0V			20	pF
R ₁ ,R ₂ ,R ₃ ,R ₄	Tolerance ± 5%		47		Ω
R ₁₀	Tolerance ± 5%		13		kΩ
R ₂₀	Tolerance ± 5%		56		kΩ

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Figure 3: S21 (dB) attenuation measurement and Aplac simulation

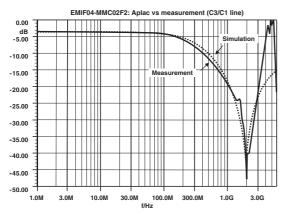


Figure 5: ESD response to IEC61000-4-2 (+15kV air discharge) on one input V(in) and on one output (Vout)

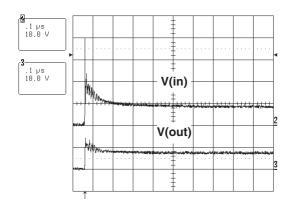


Figure 7: Junction capacitance versus reverse voltage applied (typical values)

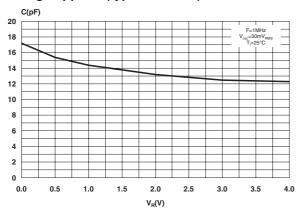


Figure 4: Crosstalk measurements

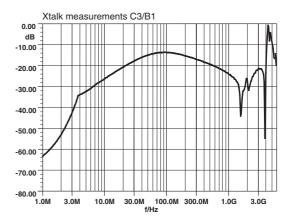
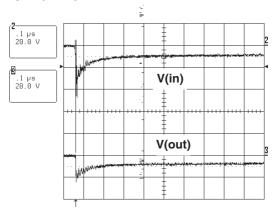


Figure 6: ESD response to IEC61000-4-2 (-15kV air discharge) on one input V(in) and on one output (Vout)



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Figure 8: Aplac model device structure

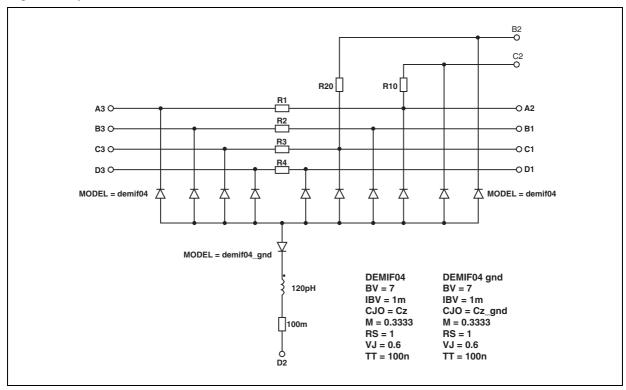
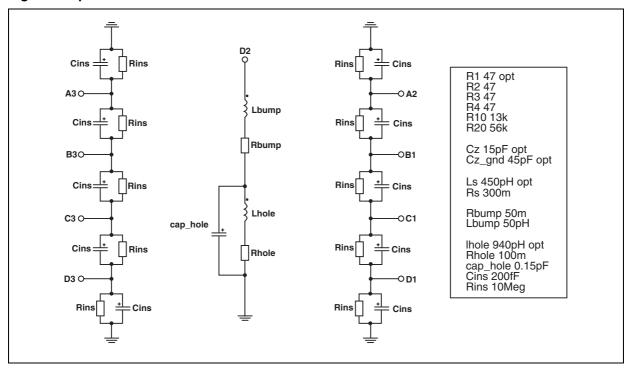


Figure 9: Aplac model connections



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Figure 10: Order Code

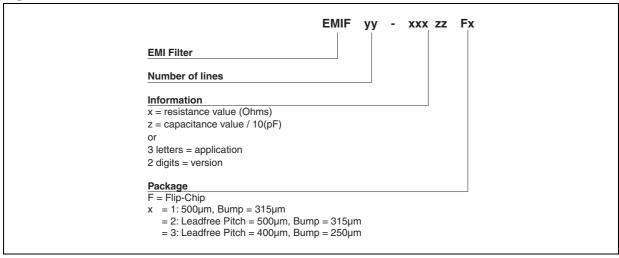


Figure 11: FLIP-CHIP Package Mechanical Data

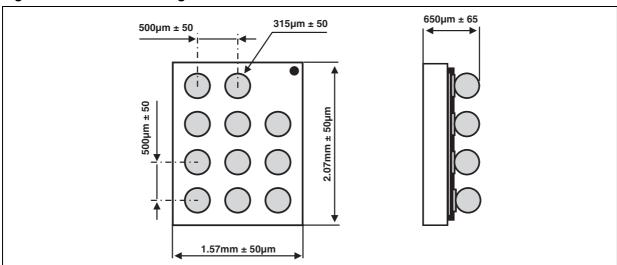


Figure 12: Foot Print Recommendations

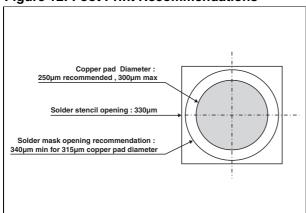
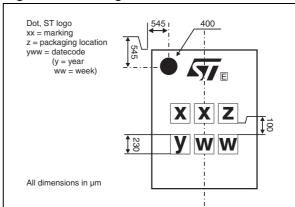


Figure 13: Marking



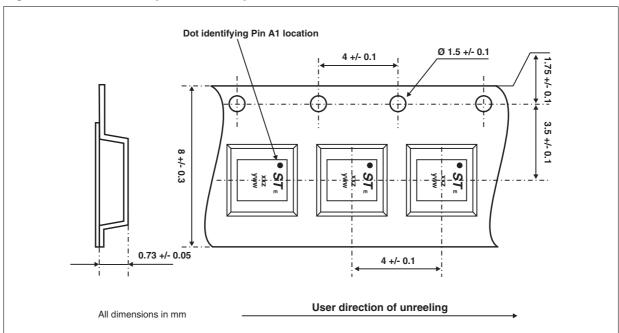


Figure 14: FLIP-CHIP Tape and Reel Specification

Table 4: Ordering Information

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF04-MMC02F22	FH	Flip-Chip	4.5 mg	5000	Tape & reel 7"

Note: More packing informations are available in the application note AN1235: "Flip-Chip: Package description and recommendations for use" AN1751: "EMI Filters: Recommendations and measurements"

Table 5: Revision History

Date	Revision	Description of Changes
14-Oct-2004	1	First issue

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